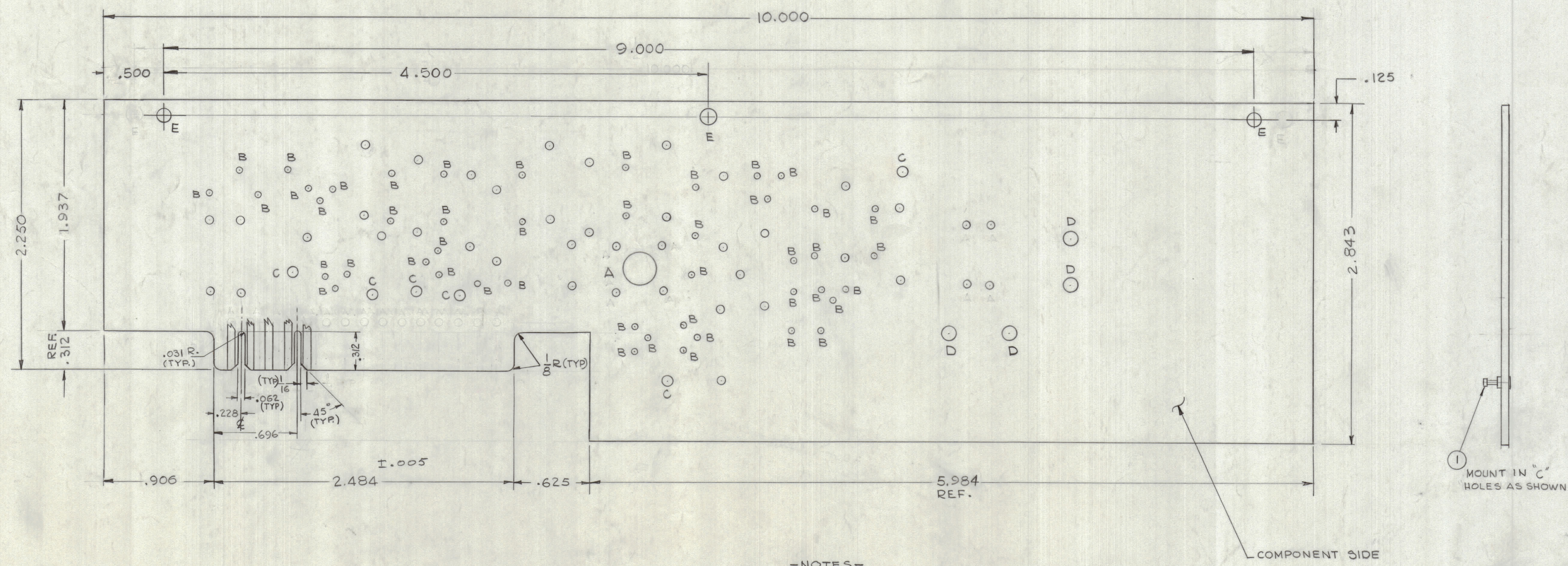


REVISIONS					
ZONE	BYM	DESCRIPTION	DATE	E.M.N. NO.	APPRO
Ø		ORIGINAL RELEASE FOR PRODUCTION	2/2/66		JLB

HOLE	DESCRIPTION	REQ
A	.256 DIA.	1
B	.040 DIA.	46
C	.081 DIA.	6
D	.109 DIA.	4
E	.125 DIA.	3
UNMARKED HOLES .052 DIA.		41



- NOTES-
- MANUFACTURED IN ACCORDANCE WITH TMC SPEC. 5735 AND SPECIFICALLY .
  - 1- OVER ALL MATERIAL THICKNESS .062 ± .0062 AS PER (PP 3.1, 3.2)
  - 2- CONDUCTIVE PATTERN TO BE COPPER FOIL AS PER (PP 4.1) PLATING TO BE TIN LEAD AS PER (DPI 3.2.2, 13.2.1)
  - 3- EDGE BOARD CONNECTOR FINGERS SHALL BE GOLD PLATED AS PER (PPI 0.1, 10.4)
  - 4- COMPONENT SIDE TO BE MARKED AS PER 5-727 (FOR MARKING SEE SHEET 1 OF 2) THIS IS SINGLE SIDE BOARD.

6	1	TE127-2	TERMINAL STUD	C
REV'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
LIST OF MATERIAL 12A600 'BUFF 100-1				
MATERIAL		SEE NOTES		
FINISH		THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK		
TITLE		PRINTED CIRCUIT BOARD, BUFFER		
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES	DRAWN	DATE	FINAL APPROVAL	DATE
CHECKED	G.D.L.	11-18-65	JLB	2/4/66
DECIMALS	± .05	FRACTIONS	± 1/64	
ANGLES	± .01	TOLERANCES	± 0° 30'	
MECH. DES.	DATE	DATE	DATE	DATE
		3/3/66		
SHEET 2 OF 2		REV. LTR.		

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